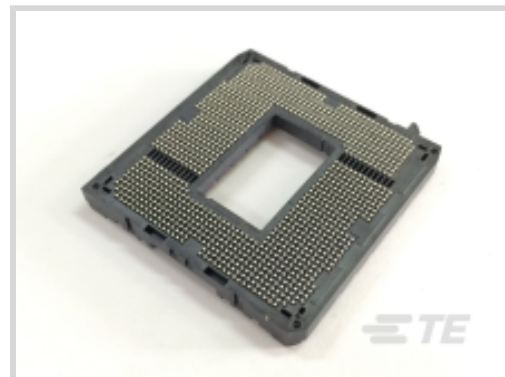




TE Internal #: 2287402-1
 LGA Sockets, LGA 1151, Board-to-Board, 1151 Position, Gold,
 Contact Mating Area Plating Material Thickness 15 µin, .91mm [.036in] Centerline

[View on TE.com >](#)

Connectors > Socket Connectors > IC Sockets > LGA Sockets



IC Socket Type: **LGA 1151**
 Connector System: **Board-to-Board**
 Number of Positions: **1151**
 Contact Mating Area Plating Material: **Gold**
 Contact Mating Area Plating Material Thickness: **[15 µin]**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| Connector & Contact Terminates To | Printed Circuit Board |
| Product Type | Socket |

Configuration Features

| | |
|---------------------|---------------------------------|
| Number of Positions | 1151 |
| Grid Spacing | .914 x .914 mm [.036 x .036 in] |

Body Features

| | |
|-------------------|--------|
| Frame Style | Square |
| Plating Material | Gold |
| Plating Thickness | 15 µin |

Contact Features

| | |
|--------------------------------------|--------------|
| Contact Base Material | Copper Alloy |
| IC Socket Type | LGA 1151 |
| Contact Mating Area Plating Material | Gold |
| | 15 µin |
| Contact Current Rating (Max) | .5 A |

Mechanical Attachment

| | |
|----------------------|---------|
| Heat Sink Attachment | Without |
|----------------------|---------|



| | |
|--------------------|---------------------------|
| PCB Mounting Style | Surface Mount Solder Ball |
|--------------------|---------------------------|

| | |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

Housing Features

| | |
|--------------------|-----------------|
| Centerline (Pitch) | .91 mm[.036 in] |
|--------------------|-----------------|

| | |
|------------------|--------------------------------|
| Housing Material | High Temperature Thermoplastic |
|------------------|--------------------------------|

| | |
|---------------|-------|
| Housing Color | Black |
|---------------|-------|

Usage Conditions

| | |
|-----------------------------|----------------------------|
| Operating Temperature Range | -25 – 100 °C[-13 – 212 °F] |
|-----------------------------|----------------------------|

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

| | |
|------------|------|
| Tray Color | Gray |
|------------|------|

| | |
|------------------|------|
| Packaging Method | Tray |
|------------------|------|

Other

| | |
|---------|----------------------|
| Comment | Lead-Free Solderball |
|---------|----------------------|

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|------------------------------|-----------|
| EU RoHS Directive 2011/65/EU | Compliant |
|------------------------------|-----------|

| | |
|-----------------------------|-----------|
| EU ELV Directive 2000/53/EC | Compliant |
|-----------------------------|-----------|

| | |
|---|---|
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
|---|---|

| | |
|--|---|
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JAN 2021 (211) Does not contain REACH SVHC |
|--|---|

| | |
|-----------------|---|
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
|-----------------|---|

| | |
|---------------------------|--------------------------------|
| Solder Process Capability | Reflow solder capable to 260°C |
|---------------------------|--------------------------------|

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Customers Also Bought



Documents

Product Drawings

[SOCKET ASSY LGA1151, 0.38AU](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2287402-1_B.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2287402-1_B.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2287402-1_B.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Product Specification](#)

English

Product Environmental Compliance

[TE Material Declaration](#)

English